

PC922

High Power OPIC Photocoupler

* Lead forming type (I type) and taping reel type (P type) are also available. (PC922I/PC922P) (Page 656)

■ Features

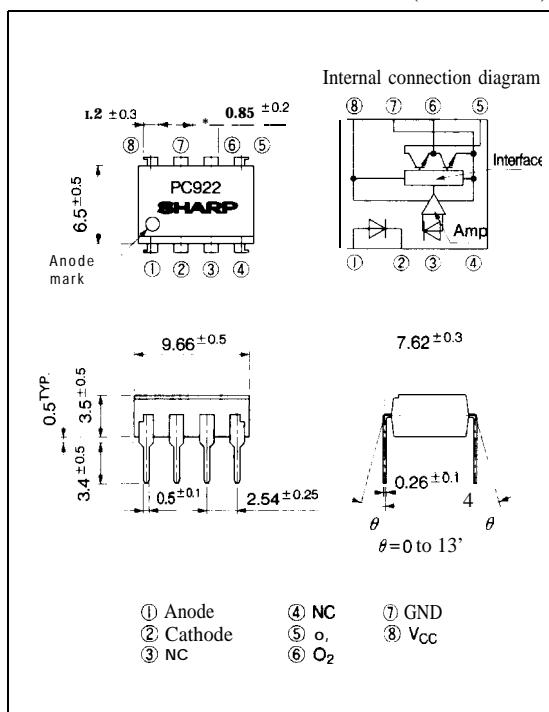
1. Built-in base amplifier for inverter drive
2. High power (I_{O1} : MAX. 0.5A(DC))
(I_{O2P} : MAX. 2.0A(pulse))
3. High isolation voltage between input and output (V_{iso} : 5000V_{rms})
4. High noise reduction type
5. High speed response (t_{PHL}, t_{PLH} : MAX. 5 μ s)
6. High sensitivity (I_{FLH} : MAX. 3mA)
7. Recognized by UL, file No. E64380

■ Applications

1. Inverter controlled air conditioners
2. Small capacitance general purpose inverters

■ Outline Dimensions

(Unit : mm)



* "OPIC" (Optical IC) is a trademark of the SHARP Corporation.
An OPIC consists of a light-detecting element and signal processing circuit integrated onto a single chip.

■ Absolute Maximum Ratings (Ta = T_{opr} unless otherwise specified)

Parameter		Symbol	Rating	Unit
Input	Forward current	I _F	25	mA
	*1 Reverse voltage	V _R	6	v
output	Supply voltage	V _{CC}	18	v
	O ₁ output current	I _{O1}	0.5	A
	*2 O ₁ peak output current	I _{O1P}	1.0	A
	O ₂ output current	I _{O2}	0.6	A
	*2 O ₂ peak output current	I _{O2P}	2.0	A
	O ₁ output voltage	V _{O1}	18	v
	Power dissipation	P _O	500	mW
	Total power dissipation	P _{tot}	550	mW
'Isolation voltage		V _{iso}	5 0 0 0	V _{rms}
Operating temperature		T _{opr}	-20 to +80	°C
Storage temperature		T _{stg}	-55 to +125	°C
*4 Soldering temperature		T _{sot}	260	°C

*1 Ta = 25°C

*2 Pulse widths 5 μ s, Duty ratio = 0.01

*3 40 to 60%RH, AC for 1 minute,
Ta = 25°C

*4 For 10 seconds

■ Electro-optical Characteristics

(Ta = T_{opr} unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Fig.	
Input	Forward voltage	V _{F1}	T _a =25°C, I _F =5mA		1.1	14	v	-	
		V _{F2}	T _a =25°C, I _F =0.2mA	0.6	0.9		v	-	
	Reverse current	I _R	T _a =25°C, V _R =3V		—	10	μA	-	
	Terminal capacitance	C _t	T _a =25°C, V=0, f=1kHz	—	30	250	pF	-	
output	Operating supply voltage	V _{CC}		5.4		13	v	-	
	01 low level output voltage	V _{O1L}	V _{CC} =6V, I _{O1} =0.4A, R _{L2} =10Ω, I _F =3mA		0.2	0.4	v	1	
	O ₂ high level output voltage	V _{O2H}	V _{CC} =6V, I _{O2} =-0.4A, I _F =5mA	4.5	5.0	—	v	2	
	02 low level output voltage	V _{O2L}	V _{CC} =6V, I _{O2} =0.5A, I _F =0	—	0.2	0.4	v	-	
	01 leak current	I _{O1L}	V _{CC} =13V, I _F =0	—	—	200	μA	3	
	O ₂ leak current	I _{O2L}	V _{CC} =13V, I _F =5mA			200	μA	4	
	High level supply current	I _{CCH}	T _a =25°C, V _{CC} =6V, I _F =5mA	—	9	13	mA	-	
			V _{CC} =6V, I _F =5mA			17	mA	-	
	Low level supply current	I _{CCI}	T _a =25°C, V _{CC} =6V, I _F =0	—	11	15	mA	-	
Transfer characteristics	*5 "Low → High" threshold input current	I _{FLH}	T _a =25°C, V _{CC} =6V, R _{L1} =5Ω, R _{L2} =10Ω	0.3	1.5	3.0	mA	5	
			V _{CC} =6V, R _{L1} =5Ω, R _{L2} =10Ω	0.2	—	5.0	mA	5	
	Isolation resistance	R _{ISO}	T _a =25°C, DC=500V 40 to 60%RH	5 x 10 ¹⁰	10 ¹¹	—	Ω	-	
	Response time	t _{PLH}	T _a =25°C, V _{CC} =6V I _F =5mA R _{L1} =5Ω R _{L2} =10Ω		2	5	μs	6	
	"High → Low" propagation delay time	t _{PHL}			2	5	μs		
	Rise time	t _r			0.2	1	μs		
	Fall time	t _f			0.1	1	μs		
Instantaneous common mode rejection voltage "Output : High level"			C _{MH}	T _a =25°C, V _{CM} =600V _(peak) I _F =5mA, R _{L1} =470Ω, R _{L2} =1kΩ, ΔV _{O2H} =0.5V	- 1 500	—		V/ μs	7
Instantaneous common mode rejection voltage "Output : Low level"			C _{ML}	T _a =25°C, V _{CM} =600V _(peak) I _F =0, R _{L1} =470Ω, R _{L2} =1 kΩ ΔV _L =0.5V	1 500	—		V/ μs	7

*5 I_{FLH} represents forward current when output goes from low to high

■ Truth Table

Input	O ₂ Output	Tr. 1	Tr. 2
ON	High level	ON	OFF
OFF	Low level	OFF	ON

■ Test Circuit

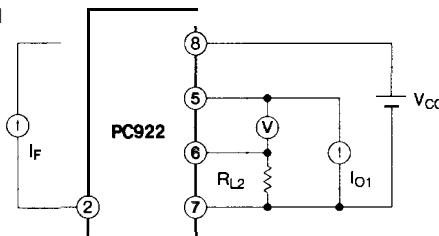
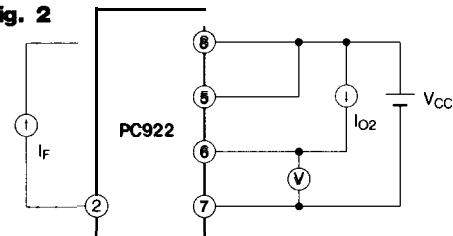
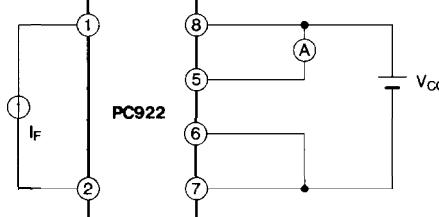
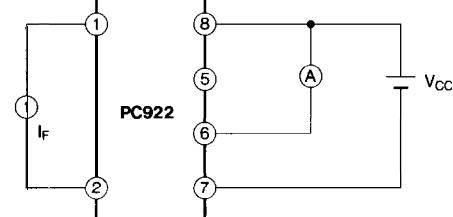
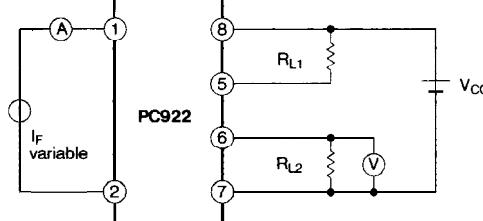
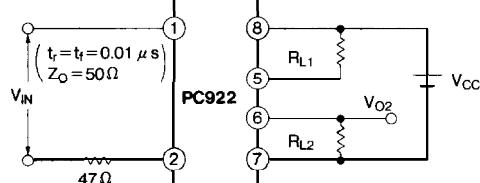
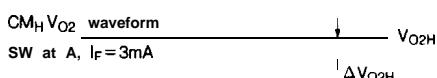
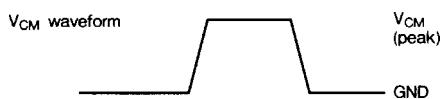
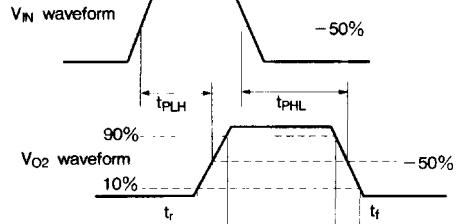
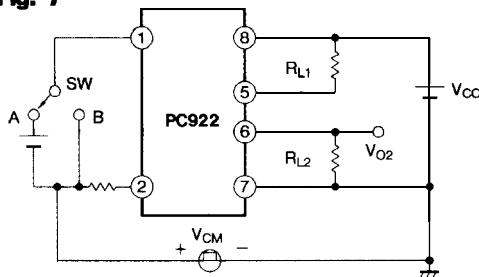
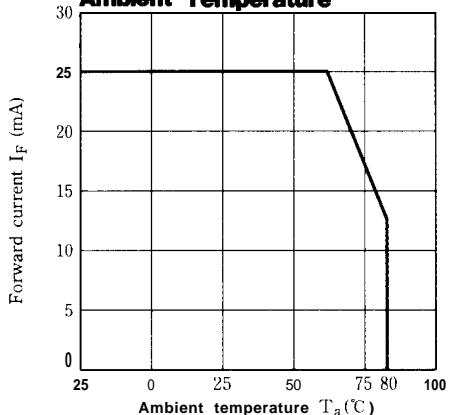
Fig. 1**Fig. 2****Fig. 3****Fig. 4****Fig. 5****Fig. 6****Fig. 7****Fig. 8 Forward Current vs. Ambient Temperature**

Fig. 9-a Power Dissipation vs. Ambient Temperature

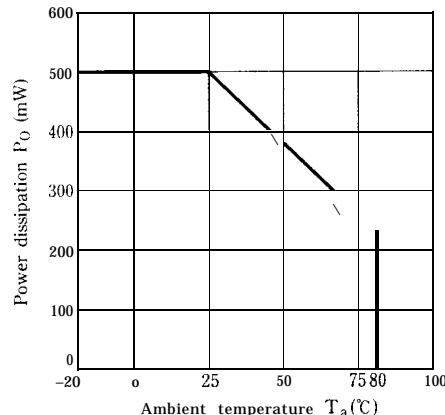


Fig. 10 Forward Current vs. Forward Voltage

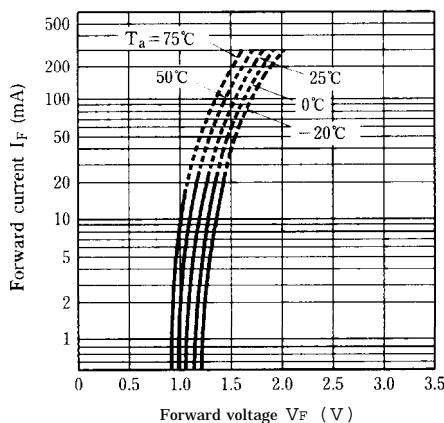


Fig.12 "Low→High" Relative Threshold Input Current vs. Ambient Temperature

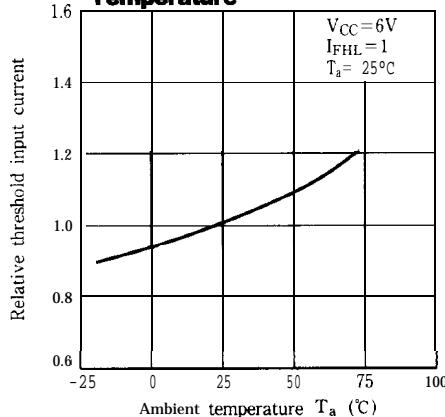


Fig. 9-b Power Dissipation vs. Ambient Temperature

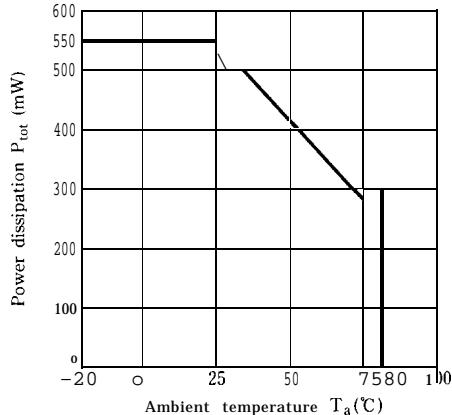


Fig.11 "Low→High" Relative Threshold Input Current vs. Supply Voltage

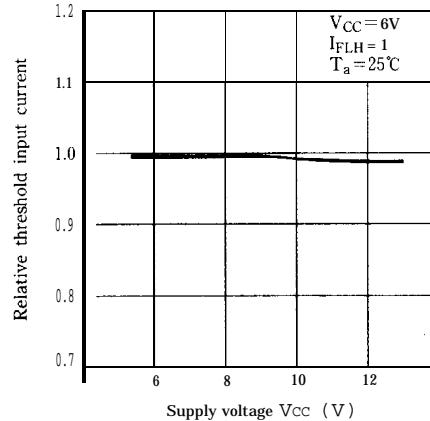


Fig.13 O₁ Low Level Output Voltage vs. O₁ Output Current

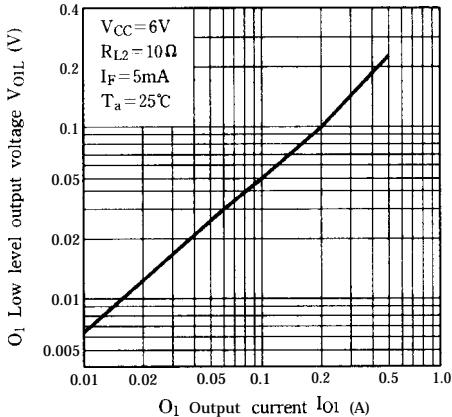


Fig.14 O₁ Low Level Output Voltage vs. Ambient Temperature

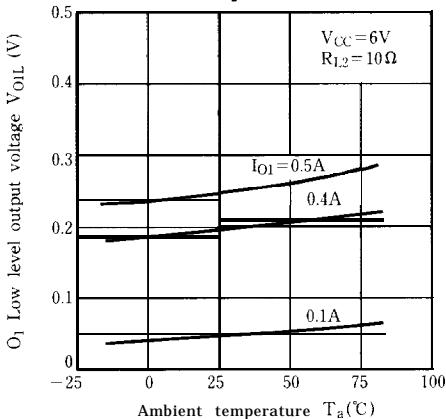


Fig.16 O₂ High Level Output Voltage vs. Ambient Temperature

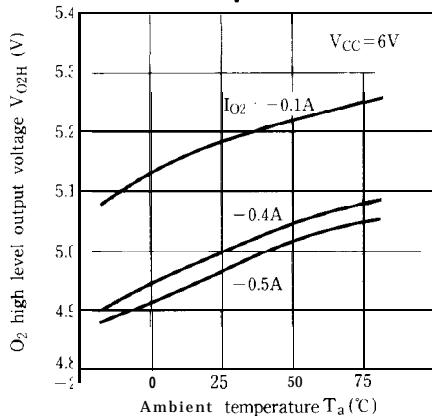


Fig.18 O₂ Low Level Output Voltage vs. Ambient Temperature

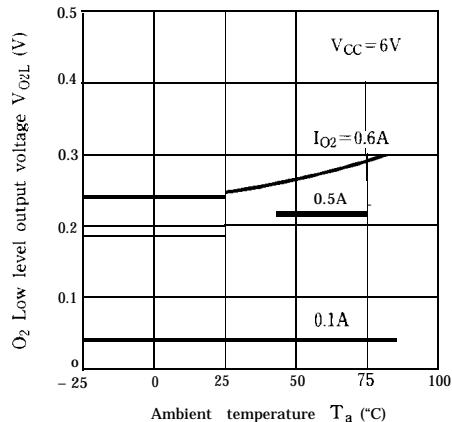


Fig.15 O₂ High Level Output Voltage vs. Output Current

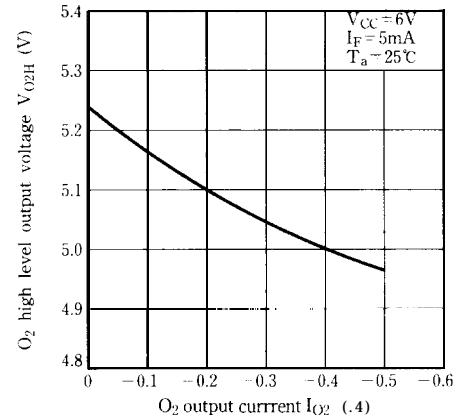


Fig.17 O2 Low Level Output Voltage VS. O2 Output Current

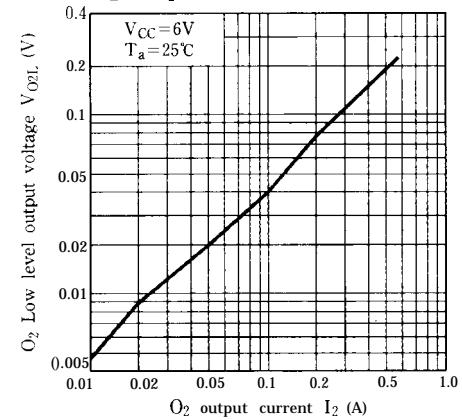


Fig.19 High Level Supply Current vs. Supply Voltage

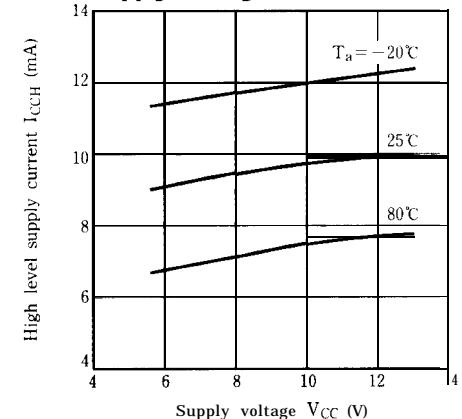


Fig.20 Low Level Supply Current vs. Supply Voltage

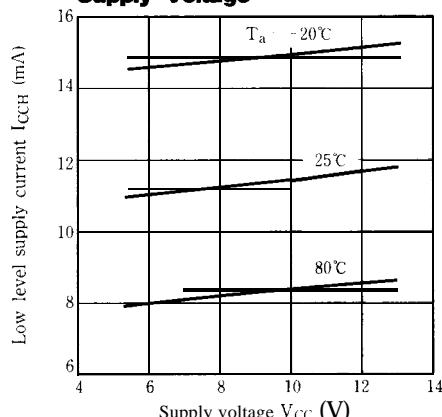
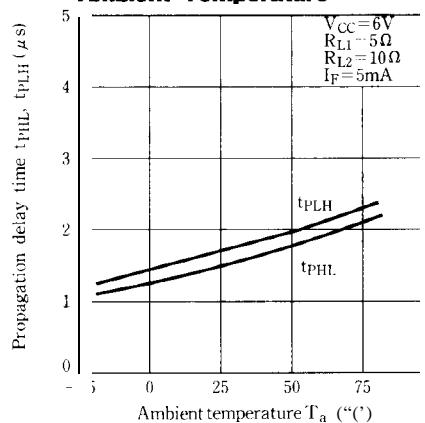
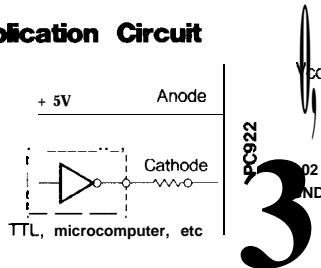


Fig.22 Propagation Delay Time vs. Ambient Temperature



■ Application Circuit



■ Precautions for Use

- (1) It is recommended that a by-pass capacitor of more than $0.01 \mu F$ is added between V_{CC} and GND near the device in order to stabilize power supply line.
- (2) Handle this product the same as with other integrated circuits against static electricity.
- (3) As for other general cautions, refer to the chapter "Precautions for Use" .(Page 78 to 93)

Fig.21 Propagation Delay Time vs. Forward Current

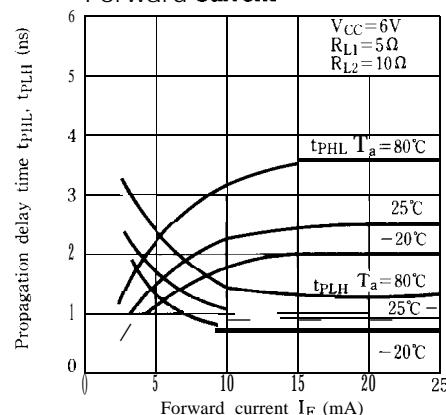


Fig.23 O₂ Peak Output Current vs. O₂ Low Level Output Voltage

